

IN THE CLAIMS:

Claims 1-4 (cancelled)

5. (currently amended) A method for forming a multilayer wiring structure, comprising:

~~a first substrate forming process comprising:~~

preparing a first substrate at least one surface of which is an first adhesive face having specified adhesion that is decreased by application of a process, the process being selected from the group consisting of ultraviolet rays, heat treatment and combinations thereof;

disposing droplets of a first liquid containing electrically conductive ~~ultra-fine~~ particles dispersed in a solvent ~~in a specified pattern~~ on the first adhesive face of the ~~substrate by a droplet discharge system; and~~

vaporizing the solvent from the droplets to form a first wiring pattern on the first adhesive face ~~formed of the particle layer on the substrate;~~

~~a second substrate forming process comprising:~~

preparing a second substrate at least one surface of which is an second adhesive face having specified adhesion;

~~forming a specified through hole in the substrate;~~

disposing droplets of a second liquid containing electrically conductive ~~ultra-fine~~ particles dispersed in a solvent on the second adhesive face of the ~~substrate in the region including the through hole in a specified pattern by a droplet discharge system; and~~

vaporizing the solvent from the droplets to form a second wiring pattern on the second adhesive face ~~formed of the particle layer on the substrate;~~

~~a process of stacking the first substrate and the second substrate with an adhesive such that the first adhesive face faces surface of the first substrate having the wiring pattern and the surface a first face of the second substrate opposite the second adhesive face having no wiring pattern face each other and the and a through hole overlaps and the first wiring pattern on the first substrate are overlapped with each other; and~~

~~a process of filling the through hole with an electrically conductive material to connect the wiring pattern on the first substrate with the wiring pattern on the second substrate removing the first wiring pattern from the first substrate such that the first wiring pattern is transferred to the first face of the second substrate.~~

6. (currently amended) The A method for forming a multilayer wiring structure according to Claim 5, wherein the first adhesive face of said first substrate and the second adhesive face of said second substrate are formed of an adhesive layer made of acryl-based, silicone-based, rubber-based, petrolatum-based, vinyl-ether-based, and hot-melt-based adhesives.

7. (currently amended) The A method for forming a multilayer wiring structure according to Claim 17 5, wherein the ~~process of filling of~~ the through hole with the an electrically conductive material is performed such that after the droplets of a third liquid containing electrically conductive ~~ultra-fine~~ particles dispersed in a solvent have been dropped ~~by a droplet discharge system~~, the solvent is vaporized from the droplets.

8. (currently amended) The A method for forming a multilayer wiring structure according to Claim ~~17~~ 6 or 7, wherein, ~~in the process of filling of~~ the through hole with the ~~an~~ electrically conductive material, the electrically conductive material is formed at least on the side wall of the through hole to thereby connect the first wiring pattern ~~on the first substrate~~ and the second wiring pattern ~~on the second substrate~~ with each other.

Claims 9-10 (cancelled)

11. (currently amended) The A method for forming a multilayer wiring structure according to Claim ~~5~~ 4, wherein the said vaporizing is performed using a hot-air oven.

12. (currently amended) The A method for forming a multilayer wiring structure according to Claim ~~5~~ 4, wherein said adhesive face is formed by applying a coating liquid to said substrate and treating said coating liquid in a hot air oven.

Claim 13 (cancelled)

14. (currently amended) A method for forming a multilayer wiring structure, comprising:

~~a first substrate forming process comprising:~~

preparing a first substrate at least one surface of which is an first adhesive face having specified adhesion that is decreased by application of a process, the process being

selected from the group consisting of ultraviolet rays, heat treatment and combinations thereof;

disposing droplets of a first liquid containing electrically conductive ~~ultra-fine~~ particles dispersed in a solvent ~~in a specified pattern~~ on the first adhesive face ~~of the~~ substrate ~~by a droplet discharge system;~~ and

vaporizing the solvent from the droplets to form a first wiring pattern ~~formed of the~~ ~~particle layer~~ on the first adhesive face substrate, ~~wherein the adhesive face of said first~~ ~~substrate comprises an adhesive layer whose adhesion has been decreased;~~

~~a second substrate forming process comprising:~~

preparing a second substrate at least one surface of which is an second adhesive face having specified adhesion;

forming a first ~~specified~~ through hole in the second substrate;

disposing droplets of a second liquid containing electrically conductive ~~ultra-fine~~ particles dispersed in a solvent on the second adhesive face ~~of the substrate~~ in a ~~the~~ region including the first through hole ~~in a specified pattern by a droplet discharge system;~~ and

vaporizing the solvent from the droplets to form a second wiring pattern on the second adhesive face ~~formed of the particle layer on the substrate;~~

preparing a third substrate at least one surface of which is a third adhesive face having specified adhesion;

forming a second through hole in the third substrate;

~~a process of stacking the first substrate and the second substrate such that the~~ first adhesive face faces a first face of the second substrate opposite the second adhesive surface of the first substrate having the wiring pattern and the surface of the second

~~substrate having no wiring pattern face each other~~ and the first through hole overlaps the first wiring pattern ~~and the wiring pattern on the first substrate are overlapped with each other;~~

filling the first through hole with a first electrically conductive material to connect the first wiring pattern with the second wiring pattern;

removing the first wiring pattern from the said first substrate from said second substrate such that the first wiring pattern layer of said first substrate is transferred adhered to the first face of the a back surface of said second substrate by applying a process, the process being selected from the group consisting of appying ultraviolet rays to the first adhesive face, heating the first adhesive face and combinations thereof;

stacking the adhering said second substrate and the to a third substrate such that the second through hole overlaps the first wiring pattern that has been transferred to the first face of the second substrate comprising a base material, and adhesive layer, and through holes formed in the base material and the adhesive layer, wherein said wiring layer adhered to the back surface of said second substrate is adhered to portions of said base material of said third substrate; and

a process of filling the second through hole with an second electrically conductive material to connect the second electrically conductive material wiring pattern on the first substrate with the first wiring pattern on the second substrate.

Claim 15 (cancelled)

Please add the following new Claims 16-21:

16. (new) The method of forming a multilayer wiring structure according to Claim 5, wherein the removing of the first wiring pattern from the first substrate includes decreasing adhesion of the first adhesive face by a process, the process being selected from the group consisting of applying ultraviolet rays, heat treatment and combinations thereof.

17. (new) The method of forming a multilayer wiring structure according to Claim 5, further comprising filling the through hole with an electrically conductive material to connect the first wiring pattern with the second wiring pattern.

18. (new) The method of forming a multilayer wiring structure according to Claim 14, wherein the stacking of the second substrate and the third substrate includes facing the first face of the second substrate and a second face of the third substrate opposite the third adhesive face.

19. (new) The method of forming a multilayer wiring structure according to Claim 14, wherein the first adhesive face and the second adhesive face are formed of an adhesive layer made of any of acryl-based, silicone-based, rubber-based, petrolatum-based, vinyl-ether-based, and hot-melt-based adhesives.

20. (new) The method of forming a multilayer wiring structure according to Claim 14, wherein the vaporizing is performed using a hot-air oven.

21. (new) The method of forming a multilayer wiring structure according to Claim 5, wherein the first adhesive face is formed by applying a coating liquid to the first base substrate and treating said coating liquid in a hot-air oven.